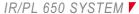
IR/PL 650 SYSTEM

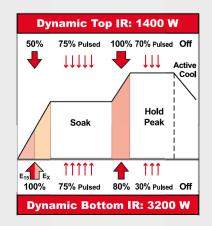




ERSA IR/PL 650

The Flagship Rework Machine

The IR/PL 650 is ERSA's flagship rework machine and affords the greatest heating power (4,600 W) for large and difficult PCBs. This machine was designed to offer the highest degree of automation in the ERSA rework line. The IR/PL 650 requires the least operator dependence and thus guarantees a stable and repeatable rework process for all applications.



The IR Rework system is broken down into four distinct operational modules:

- I. IR 650 Selective Reflow module
- II. RPC 650 Reflow Process Camera module
- III. PL 650 Precision Placement module
- IV. IRSoft Software module (see pages 16 & 17)

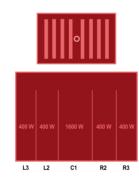
Recommended Accessories:

It is recommended to purchase: Split Optic Kit (p. 21) for placing large PQFPs, Component Centering Station (p. 21) for alignment of fine pitch components and the Rework Starter Kit (p. 20). Special desoldering tools, such as the Chip Tool for small SMD removal and the X-Tool for TH desoldering can be used with the solder station integrated into this system. For ordering details, please refer to the ERSA Soldering Tools catalogue or visit www.ersa.com. A complete listing of all rework accessories can be found on pages 20 through 23.



ERSA IR 650

Selective BGA/SMT Reflow Technology for Rework



The 4,600 W DynamicIR system has 4 top and 5 bottom heating zones

IR 650 Module Features:

- DynamicIR & Multi True Closed Loop controlled selective reflow process with APR
- 5 channel temperature recording:1 IRS sensor, 4 AccuTC thermocouples (K-type)
- Laser pointer for component ID & PCB positioning
- Motorized reflow head with component lift-off
- 9 programmable heating zones with 4,600 W
- Removable PCB fixing frame with top & bottom side center supports; max. PCB size 560 mm x 460 mm
- Integrated axial top & laminar bottom cooling fans
- Component handling vacuum pen
- Integrated digital soldering station with soldering iron
- ▼ PC ready via USB interface using IRSoft

The IR 650 Selective Reflow Module uses DynamicIR heating technology for fully automatic dynamic control of the top (1,400 W / 60 mm x 120 mm) and bottom (3,200 W / 350 mm x 450 mm) IR heaters. The total available power (4,600 W) to the selective reflow system is spread across 4 separately controllable heating zones on the top and 5 zones on the bottom. Depending on board size, the thermal mass of the substrate, and component size, the DynamicIR technology guarantees that the required heat energy is delivered at the precise time and location in order to ensure that the component and board exactly follow the prescribed temperature profile.

Now combined with the enhanced capability to run an extended or flat peak, this revolutionary technology affords the lowest temperature deltas across the component, the highest degree of process safety and greatly reduces PCB warpage.

Ordering information:

UIROSUA

IR Rework System IR 650 with RPC 650 Module
(incl. IRSoft, 2 pcs. AccuTC, 1 pc. Flexpoint TC
holder, integrated cooling fans & soldering station)